



Board Characteristics - 4 LAYER BOARD

- 0. All dimensions are given in inches unless specified otherwise.
- 1. Material FR4 , Tg > 170 C.
- 2. Minimum trace width and clearance: 0.006"
- 3. Impedance control: 50 Ohm for all 6 mil signal traces
- 4. 1 oz copper for all layers.
- 5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
- 6. Apply Solder Mask over bare copper.
- 8. Silkscreen on Component and Solder Sides.
- 10. FHS tolerances: +/- 0.003 unless specified otherwise.
- 11. Interlayer spacing as specified

BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.013	12	YES	---	
⊞	.014	304	YES	---	
⊘	.032	20	YES	---	
⊞	.041	9	YES	---	
⊖	.094	1	NO	---	
⊞	.106	4	NO	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX .XXX DO NOT SCALE DRAWING			CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP		
TREATMENT			APPROVALS	DATE	TITLE		
FINISH			DRAWN M. Bogdan	8/2/2011	PSEC3 - QFP Mezzanine Specification Drawing		
SIMILAR TO			CHECKED M. Bogdan	8/2/2011	SIZE	FSCM NO.	DWG. NO. 2726
ACT. WT	CALC WT	ISSUED			SCALE 1/2	SHEET	